

ENG. NO SEE TABLE

EDP NO.

CADFILE NO.S6748802.S01 SIMILAR ITEM

DO NOT SCALE DRAWING

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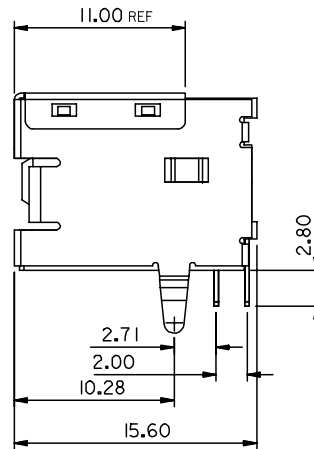
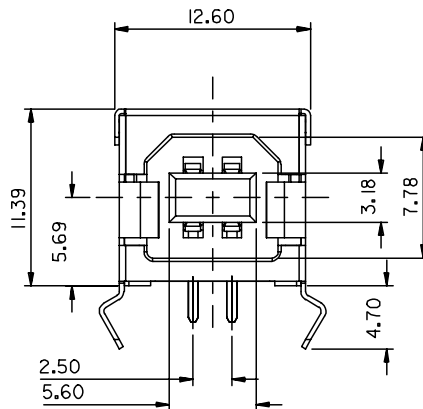
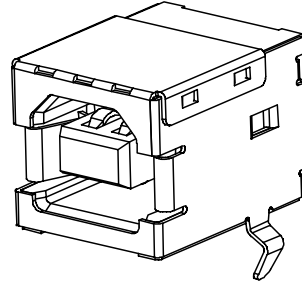
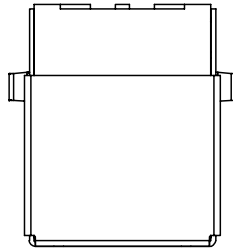
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NOTE :

1.MATERIAL :

HOUSING : HIGH TEMP. NYLON, UL94-V0,COLOR:BLACK

TERMINAL : PHOSPHOR BRONZE

METAL SHELL : COPPER ALLOY

2.PLATING :

TERMINAL :

CONTACT AREA : (a)GOLD FLASH

(b)GOLD (Au),THICKNESS=30 MICROINCH / 0.76 MICROMETER

SOLDER TAIL : (1). TIN-LEAD (Sn-Pb) ALLOY,

THICKNESS=150 MICROINCH / 3.8 MICROMETER

(2). TIN PLATING, (FOR LEAD FREE)

THICKNESS=100 MICROINCH / 2.54 MICROMETER

UNDERPLATE : NICKEL (Ni),THICKNESS=50 MICREINCH / 1.27 MICROMETER

METAL SHELL :

(1). TIN-LEAD (Sn-Pb) ALLOY,THICKNESS=100 MICROINCH / 2.54 MICROMETER

UNDERPLATE : NICKEL (Ni),THICKNESS=50 MICROINCH / 1.27 MICROMETER

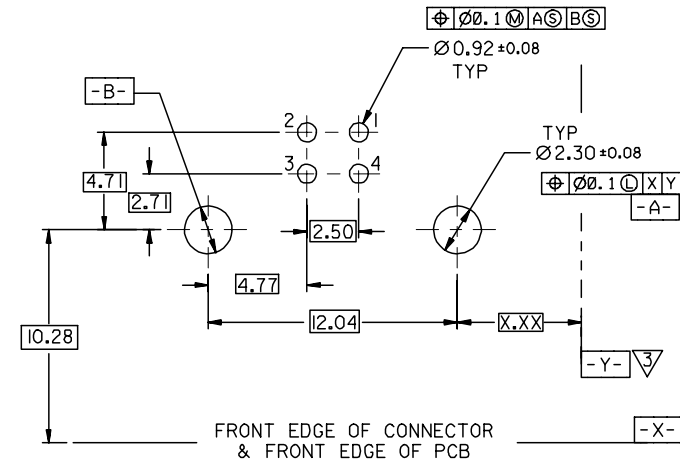
(2). PURE TIN (Sn),THICKNESS=100 MICROINCH / 2.54 MICROMETER

UNDERPLATE : NICKEL (Ni),THICKNESS=50 MICROINCH / 1.27 MICROMETER

3.DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER

RECOMMEND PCB THICKNESS : 1.6 +/- 0.05mm

4.PRODUCT SPECIFICATION : REFER TO PS-67998-0000

FRONT EDGE OF CONNECTOR
& FRONT EDGE OF PCB

RECOMMENDED PCB LAYOUT

ADD LEAD FREE PART
EC NO. JYI 2004/11/18
CHK: CH/K
APPR: D

DESCRIPTION

REV

QUALITY SYMBOLS
MAJOR = 0
CRITICAL = 0GENERAL TOLERANCES:
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± .	± .
3 PLACES	± .	± .
2 PLACES	±0.25	±.010
1 PLACE	±0.25	±.010

ANGULAR: ±3°
DRAFT WHERE APPLICABLE MUST
REMAIN WITHIN DIMENSIONSSCALE
3 : 1DESIGN UNITS
mm INCHDRAWN BY & DATE
Richard Ho 2001/02/21CHECKED BY & DATE
Vincent Lin 2001/02/21APPROVED BY & DATE
Mega Lin 2001/02/21CAD FILENAME
S6748802.S01THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.THIRD ANGLE
PROJECTIONTITLE:
USB "B" R/A CONNECTOR

MOLEX INCORPORATED

MATERIAL NO. SD-67488-002

DRAWING NO. SD-67488-002

SHEET NO. 1
SIZE A3DIMENSIONS:
mm INCH mm ONLY
SHT REV
REVISE ON
CAD ONLY